

TIDM-BLE-REEDMTR Bill of Materials

Part Reference	Quantity	Value	PCB Package	Description	MPN	Manufacturer	Part Number	RoHS Status
C2	1	DNM		CAPACITOR, DO NOT MOUNT, 0603, SMD			02-01324	
C3 C4 C5 C9 C16 C20	6	100nF	0402	CAPACITOR, CERAMIC X7R, 100nF, 6.3V, -10%/+10%, -55DEGC/+125DEGC, 0402, SMD	GRM155R70J104KA01D	MURATA	02-02323	ROHS_COMPLIANT
C6 C8	2	10uF	0603	CAPACITOR, CERAMIC X5R, 10uF, 6.3V, -20%/+20%, -55DEGC/+85DEGC, 0603, SMD	GRM188R60J106ME47D	MURATA	02-02419	ROHS_COMPLIANT
C7	1	100nF	0603	CAPACITOR, CERAMIC X7R, 100nF, 25V, -10%/+10%, -55DEGC/+125DEGC, 0603, SMD	GRM188R71E104KA01D	MURATA	02-01992	ROHS_COMPLIANT
C10 C12 C15 C22 C23 C24	6	DNM	0402	CAPACITOR, CERAMIC, N/A VALUE, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_DNM_N/A_M	Manufacturer selection	02-04164	PART NOT KNOWN
C11 C13 C21	3	1pF	0402	CAPACITOR, CERAMIC COG/NP0, 1pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H1R0CA01D	MURATA	02-04672	ROHS_COMPLIANT
C14	1	12pF	0402	CAPACITOR, CERAMIC COG/NP0, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H120JA01D	MURATA	02-04168	ROHS_COMPLIANT
C17 C18	2	12pF	0402	CAPACITOR, CERAMIC COG/NP0, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_12pF_COG/NP0_M_+/-5%_50V	MANUFACTURER SELECTION	02-03030	ROHS_COMPLIANT
C19	1	1uF	0402	CAPACITOR, CERAMIC X5R, 1uF, 10V, -10%/+10%, -55DEGC/+85DEGC, 0402, SMD	GRM155R61A105KE15D	MURATA	02-02381	ROHS_COMPLIANT
C31	1	6.8pF	0402	CAPACITOR, CERAMIC COG/NP0, 6.8pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H6R8CA01D	MURATA	02-04169	ROHS_COMPLIANT
FL1	1	BLM18HE152S N1	0603	FILTER, EMI, 1500@100MHZ, -55DEGC/+125DEGC, 0603, SMD	BLM18HE152SN1D	MURATA	04-00470	ROHS_COMPLIANT
J1	1	DNM		CONNECTOR, COAX RF, STRAIGHT, FEMALE, 1 PIN, SMD	SMA-10V21-TGG	HUS-TSAN	06-02188	N/A
L1	1	10uH	0805	INDUCTOR, CHIP, 10uH, -20%/+20%, 0.11A, -40DEGC/+85DEGC, 0805, SMD	CKS2125100M-T	TAIYO YUDEN	03-06514	ROHS_COMPLIANT
L11 L21	2	2.4nH	0402	INDUCTOR, CHIP, 2.4nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HN2N4S02D	MURATA	03-06554	ROHS_COMPLIANT
L12 L13	2	2nH	0402	INDUCTOR, CHIP, 2nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS2N0S02D	MURATA	03-06525	ROHS_COMPLIANT
P1 P2	2	SFM-110-02-S- D-A-K-TR		CONNECTOR, HEADER, FEMALE, STRAIGHT, 2 ROWS, 20 PINS, PITCH 1.27mm, SMD	SFM-110-02-SM-D-A-K-TR	SAMTEC	06-02251	ROHS_COMPLIANT

R1	1	100k	0402	RESISTOR, THICK FILM, 100k, -1%/+1%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_100k_+/-1%_50V_0.063W_M_+/-100PPM	MANUFACTURER SELECTION	01-12837	ROHS_COMPLIANT
R12	1	0	0402	RESISTOR, JUMPER, -55DEGC/+155DEGC, 0402, SMD	RK73Z1ETTP	KOA SPEER	01-01784	ROHS_COMPLIANT
U1	1	CC2650F128R GZ	QFN48	IC, DIGITAL, 2.4GHZ SIMPLELINK WIRELESS MCU, PITCH 0,5MM, QFN48, SMD	CC2650F128RGZT	TEXAS INSTRUMENTS	18-28499	ROHS_COMPLIANT
Y1	1	32.768kHz		CRYSTAL, RESONATOR, 32.768kHz, -20PPM/+20PPM, -40DEGC/+85DEGC, SMD	FC-135 32.7680KA-AG0	EPSON	12-00546	ROHS_COMPLIANT
Y2	1	24MHz		CRYSTAL, CRYSTAL OSCILLATOR, 24MHz, -15PPM/DEGC/+15PPM/DEGC, -40DEGC/+85DEGC, SMD	TSX-3225 24.0000MF15X-AC3	EPSON	12-00757	ROHS_COMPLIANT

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